

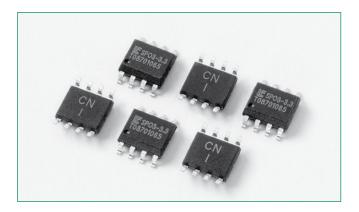
## SP03-3.3 Series 3.3V 150A Diode Array







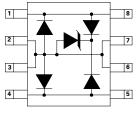




## **Agency Approvals**

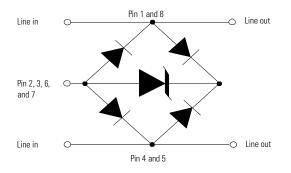
Agency	Agency File Number		
<b>71</b> .	E128662		

#### **Pinout**



SOIC-8 (Top View)

### **Functional Block Diagram**



## Additional Information







Resources

Life Support Note:

### Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

## **Description**

This new broadband protection component from Littelfuse provides overvoltage protection for applications such as 10/100/1000 BaseT Ethernet, T3/E3 DS3 interfaces, ADSL2+, and VDSL2+. This new protector combines the TVS diode element with a diode rectifier bridge to provide both longitudinal and differential protection in one package. This design innovation results in a capacitive loading characteristic that is log-linear with respect to the signal voltage across the device. This reduces intermodulation (IM) distortion caused by a typical solid-state protection solution. The application schematic provides the connection information.

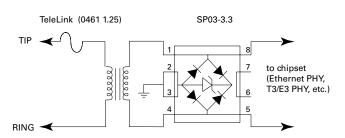
### **Features**

- RoHS compliant
- SOIC-8 surface mount package (JEDEC MS-012)
- · Low insertion loss, loglinear capacitance
- Combined longitudinal and metallic protection
- IEC 61000-4-5, 2nd edition: 8/20 surge, 150A surge immunity
- · Clamping speed of nanoseconds
- UL 94V-0 epoxy molding
- UL Recognized epoxy meeting flammability rating V-0
- Low clamping voltage
- Lead-free

### **Applications**

- T1/E1 Line cards
- T3/E3 and DS3 Interfaces
- STS-1 Interfaces
- 10/100/1000 BaseT Ethernet

### Application Example



This schematic shows a high-speed data interface protection solution. The SP03-3.3 provides both metallic (differential) and longitudinal (common mode) protection from lightning induced surge events. Its surge rating is compatible with the intra-building surge requirements of Telcordia's GR-1089-CORE, and the Basic Level Recommendations of ITU K.20 and .21. This component protects against both positive and negative induced surge events. The TeleLink fuse provides overcurrent protection for the long term 50/60 Hz power fault events.

# TVS Diode Array (SPA®Diodes) Lightning Surge Protection - SP03-3.3 Series

Absolute Maximum Ratings				
Parameter	Rating	Units		
Peak Pulse Current (8/20µs)	150	А		
Peak Pulse Power (8/20µs)	3300	W		
IEC 61000-4-2, Contact Discharge, (Level 4)	30	kV		
IEC 61000-4-2, Air Discharge, (Level 4)	30	kV		
IEC 61000-4-5, 2nd edition (8/20µs)	150	А		

100

40

Α

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause
permanent damage to the device. This is a stress only rating and operation of the device
at these or any other conditions above those indicated in the operational sections of this
specification is not implied

Thermal Information				
Parameter	Rating	Units		
SOIC Package	170	°C/W		
Operating Temperature Range	-40 to 125	°C		
Storage Temperature Range	-55 to 150	°C		
Maximum Junction Temperature	150	°C		
Maximum Lead Temperature (Soldering 20- 40s) (SOIC - Lead Tips Only)	260	°C		

## Electrical Characteristics ( $T_{OP} = 25$ °C)

Telcordia GR 1089 (Intra-Building) (2/10µs)

ITU K.20 (5/310µs)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>	-	-	-	3.3	V
Reverse Breakdown Voltage	V <sub>BR</sub>	Ι <sub>Τ</sub> = 2μΑ	3.3	-	-	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>τ</sub> = 50μΑ	3.3	-	-	V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 3.3V, T= 25°C	-	-	1	μА
Clamping Voltage, Line-Ground	V <sub>c</sub>	I <sub>pp</sub> = 50A, t <sub>p</sub> =8/20 μs	-	-	11.5	V
Clamping Voltage, Line-Ground	V <sub>c</sub>	I <sub>pp</sub> = 100A, t <sub>p</sub> =8/20 μs	-	-	15	V
Clamping Voltage, Line-Line	V <sub>c</sub>	I <sub>pp</sub> = 50A, t <sub>p</sub> =8/20 μs	-	-	13.5	V
Clamping Voltage, Line-Line	V <sub>c</sub>	I <sub>pp</sub> = 100A, t <sub>p</sub> =8/20 μs	-	-	18	V
Lucation Constitution	6	Between I/O Pins and Ground $V_R=0V$ , $f=1MHz$	-	16	25	pF
Junction Capacitance	C <sub>j</sub>	Between I/O Pins V <sub>R</sub> =0V, f= 1MHz	-	8	12	pF

Figure 1: Non-repetitive Peak Pulse Current vs. Pulse Time



Figure 2: Current Derating Curve

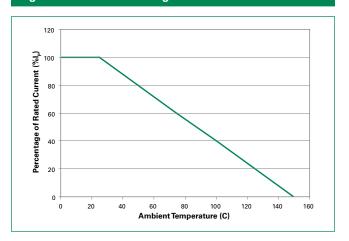




Figure 3: Pulse Waveform

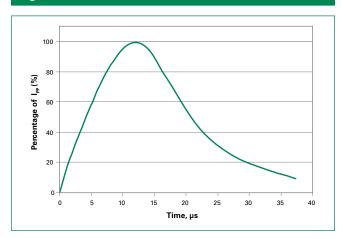


Figure 4: Clamping Voltage vs. Peak Pulse Current

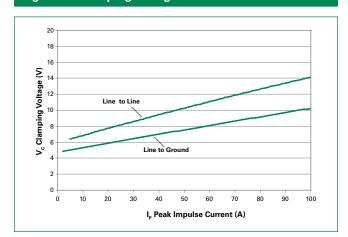


Figure 5: Capacitance vs. Reverse Voltage

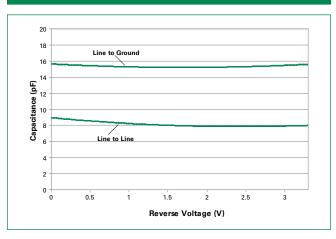
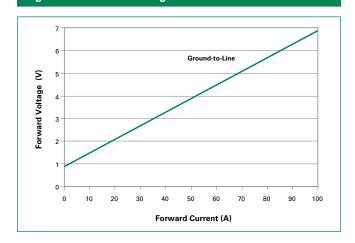
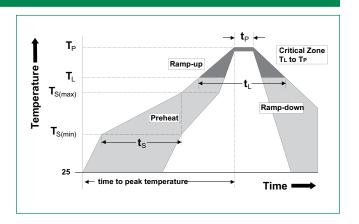


Figure 6: Forward Voltage vs. Forward Current



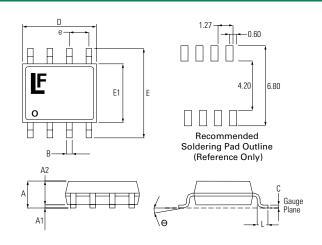
## **Soldering Parameters**

Reflow Condition		Pb – Free assembly	
	-Temperature Min (T <sub>s(min)</sub> )	150°C	
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	-Time (min to max) (t <sub>s</sub> )	60 - 180 secs	
Average rar	Average ramp up rate (Liquidus) Temp (T <sub>L</sub> ) to peak		
T <sub>S(max)</sub> to T <sub>L</sub>	T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
nellow	-Temperature (t <sub>L</sub> )	60 – 150 seconds	
Peak Tempe	erature (T <sub>P</sub> )	260 <sup>+0/-5</sup> °C	
Time within	Time within 5°C of actual peak Temperature (t <sub>p</sub> )		
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T <sub>p</sub> )		8 minutes Max.	
Do not exce	260°C		



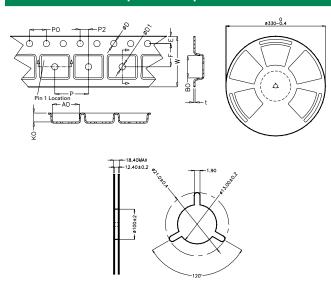


## Package Dimensions — Mechanical Drawings and Recommended Solder Pad Outline



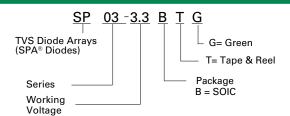
Package	SOIC-8				
Pins	8				
JEDEC	MS-012				
	Millimetres Inches			hes	
	Min	Max	x Min Max		
Α	1.35	1.75	0.053	0.069	
A1	0.10	0.25	0.004	0.010	
A2	1.25	1.65	0.050	0.065	
В	0.31	0.51	0.012	0.020	
C	0.17	0.25	0.007	0.010	
D	4.80	5.00	0.189	0.197	
E	5.80	6.20	0.228	0.244	
E1	3.80	4.00	0.150	0.157	
е	1.27 BSC 0.050 BSC			BSC	
L	0.40	1.27	0.016	0.050	

## **Embossed Carrier Tape & Reel Specification — SOIC Package**



	Millimetres		Incl	hes
	Min	Max	Min	Max
Е	1.65	1.85	0.065	0.073
F	5.4	5.6	0.213	0.22
P2	1.95	2.05	0.077	0.081
D	1.5	1.6	0.059	0.063
D1	1.50 Min		0.059 Min	
P0	3.9	4.1	0.154	0.161
10P0	40.0 ± 0.20		1.574 ± 0.008	
W	11.9	12.1	0.468	0.476
Р	7.9	8.1	0.311	0.319
A0	6.3	6.5	0.248	0.256
В0	5.1	5.3	0.2	0.209
K0	2	2.2	0.079	0.087
t	0.30 ± 0.05		0.012 ± 0.002	

## **Part Numbering System**



## **Part Marking System**



### **Ordering Information**

Part Number	Package	Marking	Min. Order Qty.
SP03-3.3BTG	SOIC-8 Tape & Reel	SP03-3.3	2500

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ESD119B1W01005E6327XTSA1 ESD5V0J4-TP ESD5V0L1B02VH6327XTSA1 ESD7451N2T5G 19180-510 CPDT-5V0USP-HF
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